

### description/ordering information

Each fixed-voltage precision regulator in the TL780 series is capable of supplying 1.5 A of load current. A unique temperature-compensation technique, coupled with an internally trimmed band-gap reference, has resulted in improved accuracy when compared to other three-terminal regulators. Advanced layout techniques provide excellent line, load, and thermal regulation. The internal current-limiting and thermal-shutdown features essentially make the devices immune to overload.

TJ	V <sub>O</sub> TYP (V)	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PowerFLEX™ (KTE)	Reel of 2000	TL780-05CKTER	TL780-05C
0°C to 125°C	5	TO-220 (KC)	Tube of 50	TL780-05CKC	TL780-05C
		TO-220, short shoulder (KCS)	Tube of 20	TL780-05KCS	TL780-05
	10	TO-220 (KC)	Tube of 50	TL780-12CKC	TL780-12C
	12	TO-220, short shoulder (KCS) Tube of 20		TL780-12KCS	TL780-12
	15	TO-220 (KC)	Tube of 50	TL780-15CKC	TL780-15C
		TO-220, short shoulder (KCS)	Tube of 20	TL780-15KCS	TL780-15

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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#### schematic



#### absolute maximum ratings over operating temperature range (unless otherwise noted)<sup>†</sup>

Input voltage, V <sub>1</sub>	. 35 V
Operating virtual junction temperature, T <sub>J</sub>	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub>	150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### package thermal data (see Note 1)

PACKAGE	BOARD	θJC	θJA	θ <b>JP</b> ‡
PowerFLEX™ (KTE)	High K, JESD 51-5	3°C/W	23°C/W	
TO-220 (KC/KCS)	High K, JESD 51-5	17°C/W	19°C/W	3°C/W

NOTE 1: Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.

<sup>‡</sup> For packages with exposed thermal pads, such as QFN, PowerPAD, or PowerFLEX,  $\theta_{JP}$  is defined as the thermal resistance between the die junction and the bottom of the exposed pad.



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### recommended operating conditions

			MIN	MAX	UNIT
		TL780-05C	7	25	
VI	nput voltage	TL780-12C	14.5	30	V
		TL780-15C	17.5	30	
ю	Output current			1.5	А
ТJ	Operating virtual junction temperature		0	125	°C

# electrical characteristics at specified virtual junction temperature, $V_I = 10 V$ , $I_O = 500 mA$ (unless otherwise noted)

	TEOT CONDIT		- +	TL780-05C				
PARAMETER	TEST CONDIT	IONS	IJ	MIN	TYP	MAX	UNIT	
O standard to see	$I_{O} = 5 \text{ mA to 1 A},$	P ≤ 15 W,	25°C	4.95	5	5.05		
Output voltage	$V_{I} = 7 V \text{ to } 20 V$		0°C to 125°C	4.9		5.1	V	
	$V_I = 7 V$ to 25 V		2500		0.5	5		
Input voltage regulation	V <sub>I</sub> = 8 V to 12 V		25°C		0.5	5	mv	
Ripple rejection	$V_I = 8 V$ to 18 V,	f = 120 Hz	0°C to 125°C	70	85		dB	
	$I_{O} = 5 \text{ mA to } 1.5 \text{ A}$	= 5 mA to 1.5 A		4 25 1.5 15		25	m\/	
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA		25°C			IIIV		
Output resistance	f = 1 kHz		0°C to 125°C		0.0035		Ω	
Temperature coefficient of output voltage	IO = 5 mA		0°C to 125°C		0.25		mV/°C	
Output noise voltage	f = 10  Hz to 100 kHz		25°C		75		μV	
Dropout voltage	I <sub>O</sub> = 1 A		25°C		2		V	
Input bias current			25°C		5	8	mA	
Level bing assessed above	V <sub>I</sub> = 7 V to 25 V		000 1- 40500		0.7	1.3		
Input blas-current change	$I_{O} = 5 \text{ mA to 1 A}$		0°C to 125°C		0.003	0.5	mA	
Short-circuit output current			25°C		750		mA	
Peak output current			25°C		2.2		А	

<sup>†</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.22-μF capacitor across the output.



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# electrical characteristics at specified virtual junction temperature, $V_I$ = 19 V, $I_O$ = 500 mA (unless otherwise noted)

	TEAT CONDITIONS	- +	TL780-12C				
PARAMETER	TEST CONDITIONS	IJ	MIN	TYP	MAX	UNIT	
Output weltere	$I_{O} = 5 \text{ mA to 1 A}, P \le 15 \text{ W},$	25°C	11.88	12	12.12	N/	
Output voltage	$V_{I} = 14.5 V \text{ to } 27 V$	0°C to 125°C	11.76		12.24	V	
	V <sub>I</sub> = 14.5 V to 30 V	2500		1.2	12		
Input voltage regulation	V <sub>I</sub> = 16 V to 22 V	25°C		1.2	12	mV	
Ripple rejection	$V_{I} = 15 V \text{ to } 25 V$ , $f = 120 \text{ Hz}$	0°C to 125°C	65	80		dB	
	IO = 5 mA to 1.5 A	0500		6.5	60		
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA	25°C		2.5	36	mv	
Output resistance	f = 1 kHz	0°C to 125°C		0.0035		Ω	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		0.6		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		180		μV	
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V	
Input bias current		25°C		5.5	8	mA	
least block and a block and	V <sub>I</sub> = 14.5 V to 30 V	000 10 40500		0.4	1.3		
Input bias-current change	$I_{O} = 5 \text{ mA to } 1 \text{ A}$	0°C to 125°C		0.03	0.5	mA	
Short-circuit output current		25°C		350		mA	
Peak output current		25°C		2.2		А	

<sup>†</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.22-μF capacitor across the output.

# electrical characteristics at specified virtual junction temperature, $V_I = 23 V$ , $I_O = 500 mA$ (unless otherwise noted)

		_ +	TL780-15C			
PARAMETER	TEST CONDITIONS	Тј	MIN	TYP	MAX	UNIT
	$I_{O} = 5 \text{ mA to 1 A}, \qquad P \le 15 \text{ W},$	25°C	14.85	15	15.15	
Output voltage	V <sub>I</sub> = 17.5 V to 30 V	0°C to 125°C	14.7		15.3	V
	$V_{I} = 17.5 V \text{ to } 30 V$	0500		1.5	15	
Input voltage regulation	$V_{I} = 20 V \text{ to } 26 V$	25°C		1.5	15	mV
Ripple rejection	V <sub>I</sub> = 18.5 V to 28.5 V, f = 120 Hz	0°C to 125°C	60	75		dB
	I <sub>O</sub> = 5 mA to 1.5 A			7	75	mV
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA	25°C		2.5	45	
Output resistance	f = 1 kHz	0°C to 125°C	(	0.0035		Ω
Temperature coefficient of output voltage	IO = 5 mA	0°C to 125°C		0.62		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		225		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Input bias current		25°C		5.5	8	mA
	V <sub>I</sub> = 17.5 V to 30 V			0.4	1.3	
Input bias-current change	$I_{O} = 5 \text{ mA to } 1 \text{ A}$	0°C to 125°C		0.02	0.5	mA
Short-circuit output current		25°C		230		mA
Peak output current		25°C		2.2		А

<sup>†</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.22-μF capacitor across the output.



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### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Permanent damage can occur when OUTPUT is pulled below ground.
  - B. C1 is required when the regulator is far from the power-supply filter.
  - C. C2 is not required for stability; however, transient response is improved.

Figure 1. Test Circuit



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#### operation with a load common to a voltage of opposite polarity

In many cases, a regulator powers a load that is not connected to ground, but instead, is connected to a voltage source of opposite polarity (e.g., operational amplifiers, level-shifting circuits, etc.). In these cases, a clamp diode should be connected to the regulator output as shown in Figure 4. This protects the regulator from output polarity reversals during startup and short-circuit operation.



Figure 4. Output Polarity-Reversal-Protection Circuit

#### reverse-bias protection

Occasionally, the input voltage to the regulator can collapse faster than the output voltage. This, for example, could occur when the input supply is crowbarred during an output overvoltage condition. If the output voltage is greater than approximately 7 V, the emitter-base junction of the series pass element (internal or external) could break down and be damaged. To prevent this, a diode shunt can be employed, as shown in Figure 5.



Figure 5. Reverse-Bias-Protection Circuit





## PACKAGE OPTION ADDENDUM

27-Feb-2006

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TL780-05CKC	NRND	TO-220	KC	3	50	TBD	CU SNPB	N / A for Pkg Type
TL780-05CKTER	NRND	PFM	KTE	3	2000	TBD	CU SNPB	Level-1-220C-UNLIM
TL780-05KCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SNPB	N / A for Pkg Type
TL780-12CKC	NRND	TO-220	KC	3	50	TBD	CU SNPB	N / A for Pkg Type
TL780-12CKCE3	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
TL780-12CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
TL780-12KCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SNPB	N / A for Pkg Type
TL780-15CKC	NRND	TO-220	KC	3	50	TBD	CU SNPB	N / A for Pkg Type
TL780-15CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
TL780-15KCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SNPB	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## **MECHANICAL DATA**

MPFM001E - OCTOBER 1994 - REVISED JANUARY 2001



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. The center lead is in electrical contact with the thermal tab.
- D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
- E. Falls within JEDEC MO-169

PowerFLEX is a trademark of Texas Instruments.



KCS (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- $\bigtriangleup$  Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- $\frown$  The chamfer is optional.
- Thermal pad contour optional within these dimensions.



## KC (R-PSFM-T3)

## PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- Α. All linear dimensions are in inches (millimeters). Β.
- This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- 🖄 The chamfer is optional.
- G Thermal pad contour optional within these dimensions.
- $\mathbb{A}$ Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



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